



PATENT
TESSERA 3:0-022

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of
Karavakis et al.

Serial No.: 08/246,113

Filed: May 19, 1994

For: Method of Encapsulating Dye and
Chip Carrier

Group Art Unit: 1208
Examiner: R. Lovering
Date: December 24, 1996

Assistant Commissioner For Patents
Washington, D.C. 20231

AMENDMENT UNDER RULE 116

Sir:

Please amend the above-identified application as follows: JAN 16 1997

In the Claims:

Amend claim 1 as follows:

1. (Amended) A method of encapsulating a semiconductor chip assembly having a top layer with an array of exposed terminals thereon, the terminals being electrically connected to the chip, said method comprising the steps of:

placing an encapsulant barrier adjacent the semiconductor chip assembly, said encapsulant barrier at least partially defining an encapsulation area;

providing a protective barrier in contact with said top layer for protecting the terminals on the top layer from an encapsulation material; and

introducing an encapsulation material into at least a portion of the encapsulation area so that the encapsulation material flows to fill the encapsulation area and

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class mail in an envelope addressed to Assistant Commissioner for Patents, Washington, D.C. 20231 on December 24, 1996.

(Signature)

MARCUS J. MILLET

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